

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	3944	(under adj bump adj metallurgy) UBM (bump adj limiting adj metallurgy) BLM	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/02 13:38
L2	2363	L1 and @ad<"20021230"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/02 10:54
L3	202	L2 and (adhesion adj layer)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/02 10:54
L4	57	L3 and polymer and (benzocyclobutene BCB polyimide pi)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/02 10:55
L5	9	L4 and pad near2 (copper cu)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/02 11:43
L6	1	@pn="5903058"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/02 11:43
L7	12	L1 and pad near2 (copper cu) and aluminum near2 nickel adj vanadium near2 copper	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/02 13:41
L8	8	L1 and pad near2 (copper cu) and titanium near2 nickel adj vanadium near2 copper	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/02 14:11

L9	1030	438/612,613,614.ccor.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/02 14:11
S1	1355	438/108.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/30 09:57
S2	1312	438/613.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/30 09:58
S3	1006	S2 and @ad<"20021230"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/30 10:00
S4	75	S3 and (adhesion adj layer)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/30 11:55
S6	3938	(under adj bump adj metallurgy) UBM (bump adj limiting adj metallurgy) BLM	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/30 11:56
S7	2363	S6 and @ad<"20021230"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/30 11:56
S8	202	S7 and (adhesion adj layer)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/30 12:05

S9	75	S8 and polymer	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/02 10:53
S11	3938	(under adj bump adj metallurgy) UBM (bump adj limiting adj metallurgy) BLM	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/31 08:17
S12	2363	S11 and @ad<"20021230"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/31 08:17
S13	202	S12 and (adhesion adj layer)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/31 08:17
S14	51	S13 and wettable near2 layer and barrier near2 layer	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/31 09:19
S15	89	S13 and (wettable solderable wett\$3) near2 layer and (barrier diffusion)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/31 09:19
S16	38	S15 not S14	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/31 09:38